



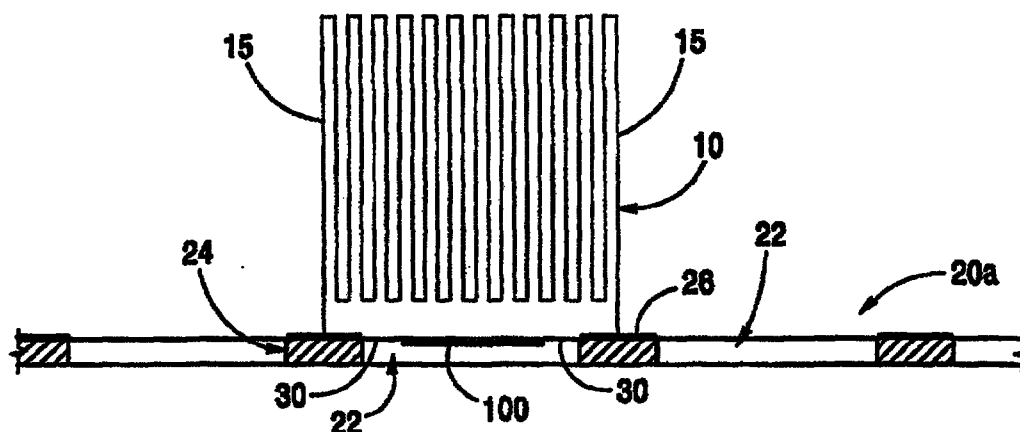
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(54) Title: **HEAT SINK PACKAGING METHODS AND DEVICES FOR SAME**

(57) Abstract

Heat sinks (10) and electrical components pre-coated with a layer of a material (100) such as thermal grease are disclosed. The coated areas may be covered with a release liner (110) that is removed prior to the assembly of the heat sink into a circuit board or other assembly. The present invention also discloses methods and devices for packaging a heat sink and an electrical component capable of mounting to the heat sink that has a layer of thermal grease disposed on its surface. The present invention also discloses improved methods of installing a heat sink using heat sinks that are pre-coated with thermal grease.